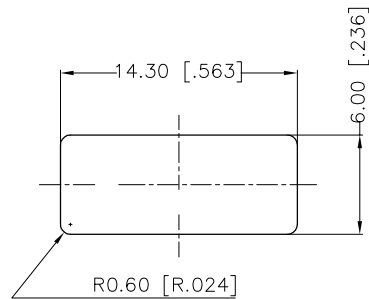


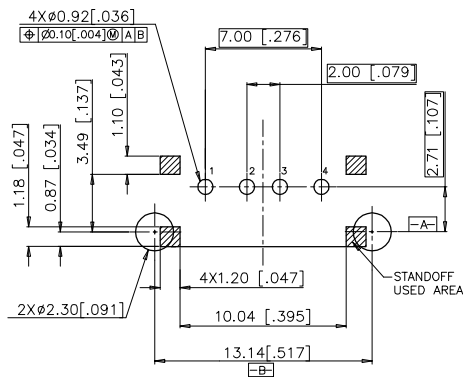
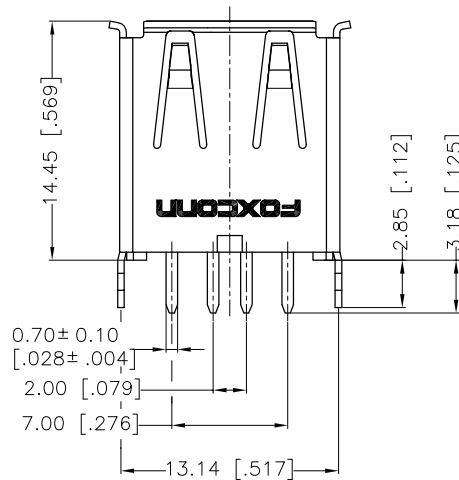
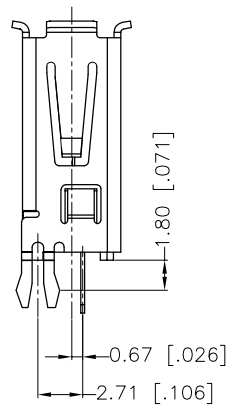
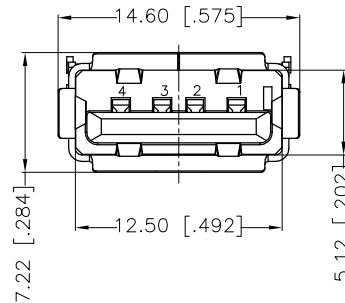
REV.	ECN NO.	APPD.
X1	2012/4/12	Adward
X2	2012/5/20	Adward

NOTES:

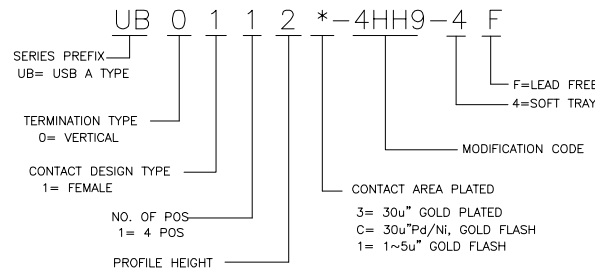
- SPECIFICATION MEETS USB STANDARD SPECIFICATION.
- ELECTRICAL CHARACTERISTIC:
  - 2-1: CONTACT CURRENT RATING: 1.5 A.
  - 2-2: CONTACT RESISTANCE: 30 MILLIOHMS MAX.
  - 2-3: DIELECTRIC WITHSTANDING VOLTAGE: 500VAC MIN.
  - 2-4: INSULATION RESISTANCE: 1000 MEGOHMS MIN.
- MECHANICAL CHARACTERISTIC:
  - 3-1: CONNECTOR ENGAGEMENT FORCE: 35N [3.5Kgf] MAX.
  - 3-2: CONNECTOR SEPARATION FORCE: 10~35N [1.0~3.5Kgf.]
  - 3-3: DURABILITY: 1500 CYCLES.
  - 3-4: OPERATING TEMPERATURE: -55°C~+85°C.
- RECOMMENDED PCB THICKNESS: 1.57±0.05 [.062±.002].
- RECOMMENDED PCB LAYOUT DIMENSION TOLERANCE ±0.05 [.002].
- RECOMMENDED PROCESS :WAVE SOLDER, PEAK TEMP. 260°, 3~5 SEC.
- THE CONNECTOR IS ROHS COMPLIANT.



MOUNTING PANEL CUTOUT  
(INTERNAL SIDE)



RECOMMENDED PCB LAYOUT  
(TOP VIEW)



ITEM	DESCRIPTION	QTY	MATERIAL	FINISH	REMARK
3	CONTACT	4	COPPER ALLOY	30u" Pd/Ni, GOLD FLASH PLATED AT CONTACT AREA, TIN ALLOY(LEAD FREE) PLATED AT TERMINATION, NICKEL PLATED OVERALL.	UB0112C-4HH9-4F
				GOLD 30u" PLATED AT CONTACT AREA, TIN ALLOY(LEAD FREE) PLATED AT TERMINATION, NICKEL PLATED OVERALL.	UB01123-4HH9-4F
				GOLD FLASH 1~5u". PLATED AT CONTACT AREA, TIN ALLOY (LEAD FREE) PLATED AT TERMINATION, NICKEL PLATED OVERALL.	UB01121-4HH9-4F
2	INSULATOR	1	THERMOPLASTIC UL 94V-0	MOLDED BLACK	
1	SHELL	1	COPPER ALLOY	NICKEL PLATED OVERALL.	
X.±		X°.±		UNITS mm [INCH]	<b>FOXCONN</b> HON HAI PRECISION IND. CO.,LTD. TAIPEI, TAIWAN, R.O.C.  TITLE: VERTICAL USB RECEPTACLE CONNECTOR  APPD: Dean Zhang 5/20'12 DWG NO.: 327-0000-1318  SCALE SHEET REV. N/A 1/1 X2
.X±		.X°.±		MAT'L	
.XX±		.XX°.±		N/A	
.XXX±		.XXX°.±		FINISH	
				N/A	
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.		Q'TY	N/A	CHKD: FH SHU 5/20'12	
				DR: Y.H. Liu 5/20'12	